

Data Sheet	January 2002

75A, 600V Hyperfast Diode

The RHRG7560 is a hyperfast diode with soft recovery characteristics (t_{rr} < 55ns). It has half the recovery time of ultrafast diodes and is of silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as a freewheeling/clamping diode and rectifier in a variety of switching power supplies and other power switching applications. Its low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits, thus reducing power loss in the switching transistors.

Formerly developmental type TA49067.

Ordering Information

PART NUMBER	PACKAGE	BRAND
RHRG7560	TO-247	RHRG7560

NOTE: When ordering, use the entire part number.

Symbol



Features

Hyperfast with Soft Recovery<	55ns
Operating Temperature17	75 ⁰ C
Reverse Voltage	00V
	Operating Temperature17

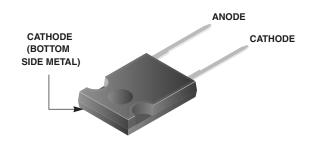
- · Avalanche Energy Rated
- Planar Construction

Applications

- Switching Power Supplies
- · Power Switching Circuits
- General Purpose

Packaging

JEDEC STYLE TO-247



Absolute Maximum Ratings T_C = 25°C, Unless Otherwise Specified

	RHRG7560	UNITS
Peak Repetitive Reverse Voltage	600	V
Working Peak Reverse Voltage	600	V
DC Blocking Voltage V _R	600	V
Average Rectified Forward Current $I_{F(AV)}$ ($T_C = 80^{\circ}C$)	75	Α
Repetitive Peak Surge Current	150	Α
Nonrepetitive Peak Surge Current	750	Α
Maximum Power Dissipation	190	W
Avalanche Energy (See Figures 10 and 11)	50	mJ
Operating and Storage Temperature	-65 to 175	oC

Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
V _F	I _F = 75A	-	-	2.1	V
	I _F = 75A, T _C = 150°C	-	-	1.7	V
I _R	V _R = 600V	-	-	250	μΑ
	V _R = 600V, T _C = 150°C	-	-	2.0	mA
t _{rr}	I _F = 1A, dI _F /dt = 200A/μs	-	-	55	ns
	$I_F = 75A$, $dI_F/dt = 200A/\mu s$	-	-	60	ns
t _a	$I_F = 75A$, $dI_F/dt = 200A/\mu s$	-	27	-	ns
t _b	$I_F = 75A$, $dI_F/dt = 200A/\mu s$	-	23	-	ns
Q _{RR}	$I_F = 75A$, $dI_F/dt = 200A/\mu s$	-	140	-	nC
СЈ	V _R = 10V, I _F = 0A	-	200	-	pF
$R_{ heta JC}$		-	-	0.8	°C/W

DEFINITIONS

 V_F = Instantaneous forward voltage (pw = 300 μ s, D = 2%).

 I_R = Instantaneous reverse current .

 t_{rr} = Reverse recovery time (See Figure 9), summation of $t_a + t_b$.

 t_a = Time to reach peak reverse current (See Figure 9).

 t_b = Time from peak I_{RM} to projected zero crossing of I_{RM} based on a straight line from peak I_{RM} through 25% of I_{RM} (See Figure 9).

Q_{RR} = Reverse recovery charge.

 C_J = Junction Capacitance.

 $R_{\theta,JC}$ = Thermal resistance junction to case.

pw = pulse width.

D = duty cycle.

Typical Performance Curves

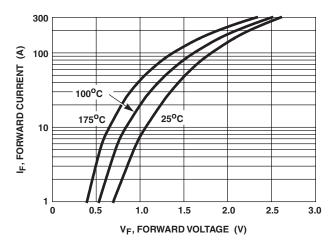


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

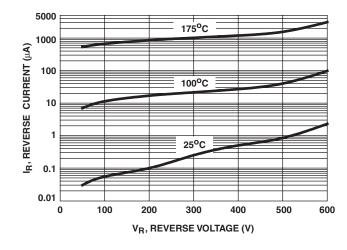


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

Typical Performance Curves (Continued)

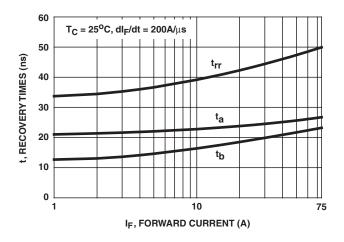


FIGURE 3. t_{rr} , t_a and t_b curves vs forward current

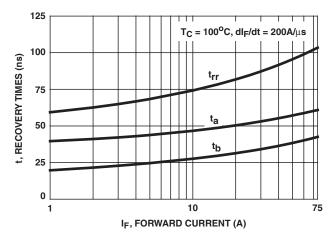


FIGURE 4. t_{rr}, t_a AND t_b CURVES vs FORWARD CURRENT

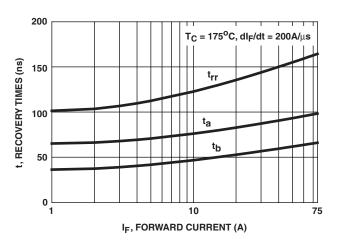


FIGURE 5. t_{rr} , t_a and t_b curves vs forward current

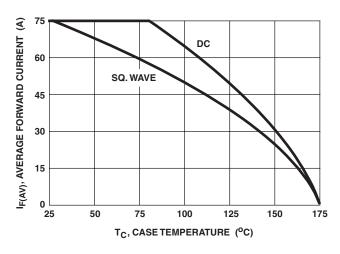


FIGURE 6. CURRENT DERATING CURVE

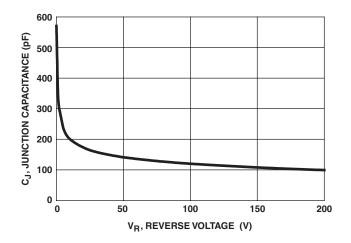


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

Test Circuits and Waveforms

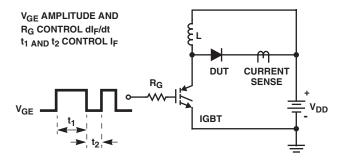


FIGURE 8. t_{rr} TEST CIRCUIT

 $I_{MAX} = 1.6A$ L = 40mH $R < 0.1\Omega$ $E_{AVL} = 1/2Li^2 \left[V_{R(AVL)} / (V_{R(AVL)} - V_{DD}) \right]$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$ $Q_1 = IGBT \left(BV_{CES} > DUT V_{R(AVL)} \right)$

FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

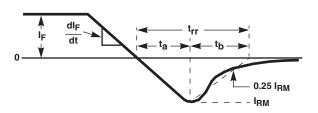


FIGURE 9. t_{rr} WAVEFORMS AND DEFINITIONS

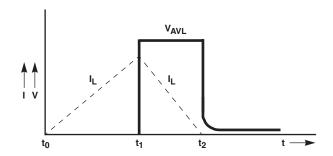


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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